

REVISION RECORD			
REV	ECD	DESCRIPTION	DRFT

NOTES:

MATERIAL:

1. HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE t=0.30mm.
3. PLATING : SELECTING GOLD PLATING 3u~50u" O NICKEL IN CONTACT AREA. 150u" TIN PLATING OVER NICKEL IN SOLDER ARE
4. SHIELD: : 0.20mm THICKNESS COPPER ALLY WITH NICKEL PL

ELECTRICAL:

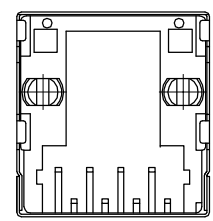
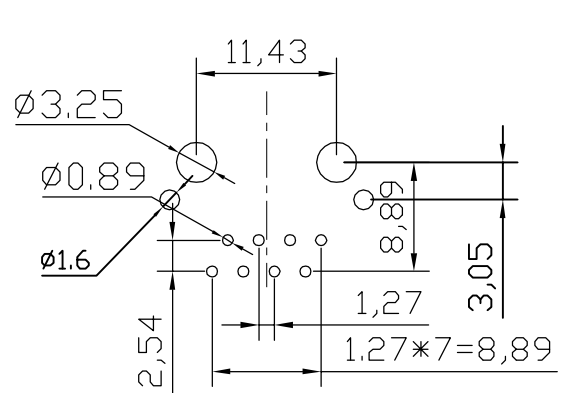
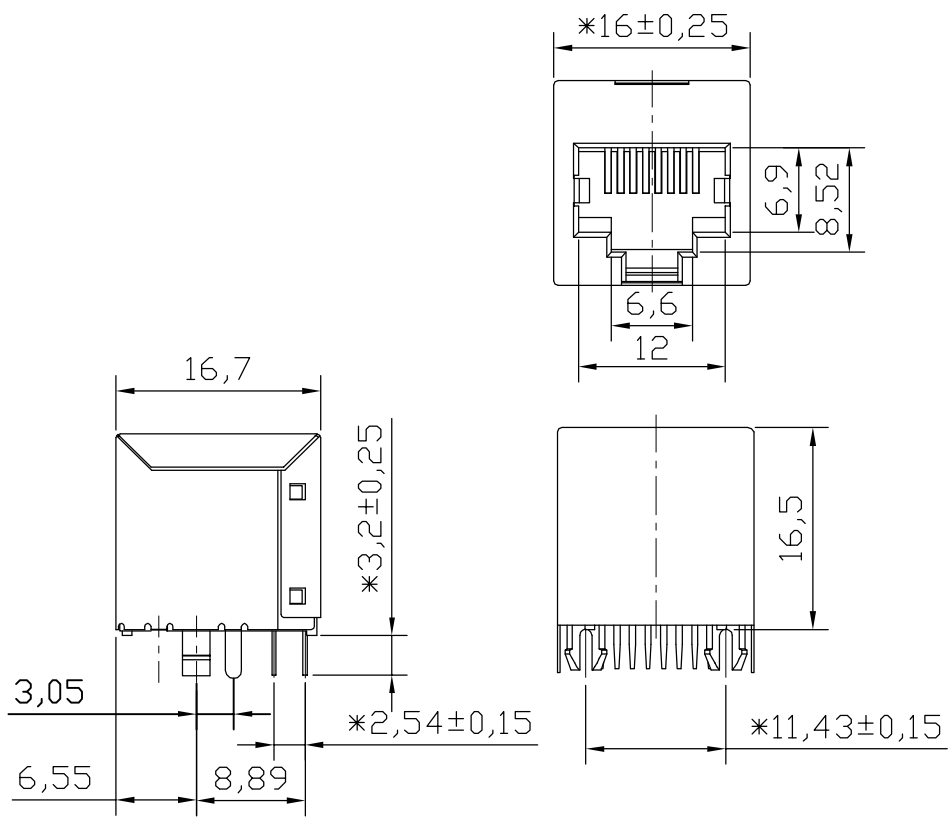
1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE : 500 MEGOHMS MIN @ 500V DC .
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

1. DURRABILITY: : 750 CYCLES MIN.
2. PCB RETENTION PRE-SOLDER : 1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40° C TO 85° C.
2. OPERATION : 0° C TO 70° C.



PC Board Layout  
Component Side Shown

MM (INCH)		DFTO: SHB	DATE: 2007.05.05	Coorle Technology	
TOLERANCES EXCEPT AS NOTED		CHKD: LANBD	DATE: 2007.05.05		
MM		MFO:	DATE:	DRAWING NO. TE52E1002	SIZE A3
.0 ± 0.15	±	APPVL:	DATE:	/PART NO.	
.00 ± 0.075	±	MATERIAL :		DO NOT SCALE DRAWING	SHEET
.000 ± 0.05	±	QTY :			□
ANGLES ± 0.5		FINISH :			
THIRD ANGLE PROJECTION		SCALE :			